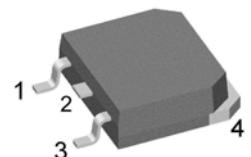


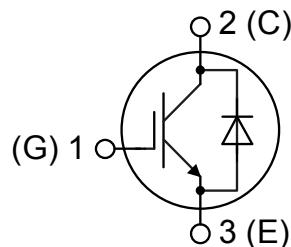
preliminary

XPT IGBT

V_{CES} = 1200V
 I_{C25} = 9A
 $V_{CE(sat)}$ = 1.8V

Copack**Part number****IXA4IF1200TC**

Backside: collector

**Features / Advantages:**

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
 - short circuit rated for 10 μ sec.
 - very low gate charge
 - low EMI
 - square RBSOA @ 3x I_c
- Thin wafer technology combined with the XPT design results in a competitive low $V_{CE(sat)}$
- SONIC™ diode
 - fast and soft reverse recovery
 - low operating forward voltage

Applications:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

Package: TO-268AA (D3Pak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

IGBT

Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$			1200	V	
V_{GES}	max. DC gate voltage				± 20	V	
V_{GEM}	max. transient gate emitter voltage				± 30	V	
I_{C25}	collector current	$T_c = 25^\circ C$			9	A	
I_{C100}		$T_c = 100^\circ C$			5	A	
P_{tot}	total power dissipation	$T_c = 25^\circ C$			45	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_c = 3A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$	1.8	2.1	V	
					2.1	V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_c = 0.1mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	5.9	6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$		0.1	mA	
					0.1	mA	
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_c = 3 A$			12	nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600 V; I_c = 3 A$ $V_{GE} = \pm 15 V; R_G = 330 \Omega$	$T_{VJ} = 125^\circ C$	70		ns	
t_r	current rise time			40		ns	
$t_{d(off)}$	turn-off delay time			250		ns	
t_f	current fall time			100		ns	
E_{on}	turn-on energy per pulse			0.4		mJ	
E_{off}	turn-off energy per pulse			0.3		mJ	
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 330 \Omega$	$T_{VJ} = 125^\circ C$				
I_{CM}		$V_{CEmax} = 1200 V$			9	A	
SCSOA	short circuit safe operating area	$V_{CEmax} = 900 V$					
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V$	$T_{VJ} = 125^\circ C$		10	μs	
I_{sc}	short circuit current	$R_G = 330 \Omega$; non-repetitive		12		A	
R_{thJC}	thermal resistance junction to case				2.7	K/W	
R_{thCH}	thermal resistance case to heatsink			0.15		K/W	

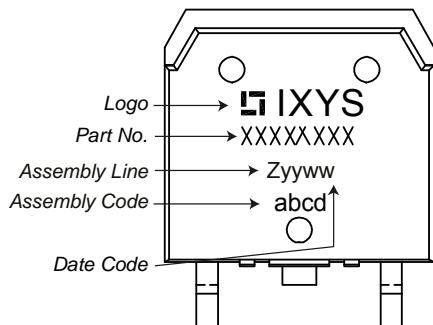
Diode

V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200	V
I_{F25}	forward current	$T_c = 25^\circ C$		10	A
I_{F100}		$T_c = 100^\circ C$		6	A
V_F	forward voltage	$I_F = 3 A$	$T_{VJ} = 25^\circ C$	2.20	V
			$T_{VJ} = 125^\circ C$	1.90	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$	*	mA
	* not applicable, see I_{CES} value above		$T_{VJ} = 125^\circ C$	*	mA
Q_{rr}	reverse recovery charge	$V_R = 600 V$ $-di_F/dt = -150 A/\mu s$ $I_F = 3 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	0.5	μC
I_{RM}	max. reverse recovery current			5	A
t_{rr}	reverse recovery time			350	ns
E_{rec}	reverse recovery energy			0.1	mJ
R_{thJC}	thermal resistance junction to case			3	K/W
R_{thCH}	thermal resistance case to heatsink			0.15	K/W

Package TO-268AA (D3Pak)

Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			70	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		150	°C
Weight				5		g
F_c	mounting force with clip		20		120	N

Product Marking



Part number

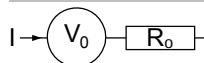
I = IGBT
 X = XPT IGBT
 A = Gen 1 / std
 4 = Current Rating [A]
 IF = Copack
 1200 = Reverse Voltage [V]
 TC = TO-268AA (D3Pak) (2)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	IXA4IF1200TC	IXA4IF1200TC	Tube	30	510224

Similar Part	Package	Voltage class
IXA4IF1200UC	TO-252AA (DPak)	1200

Equivalent Circuits for Simulation

* on die level

 $T_{VJ} = 150^\circ\text{C}$  $V_{0\max}$ threshold voltage $R_{0\max}$ slope resistance *

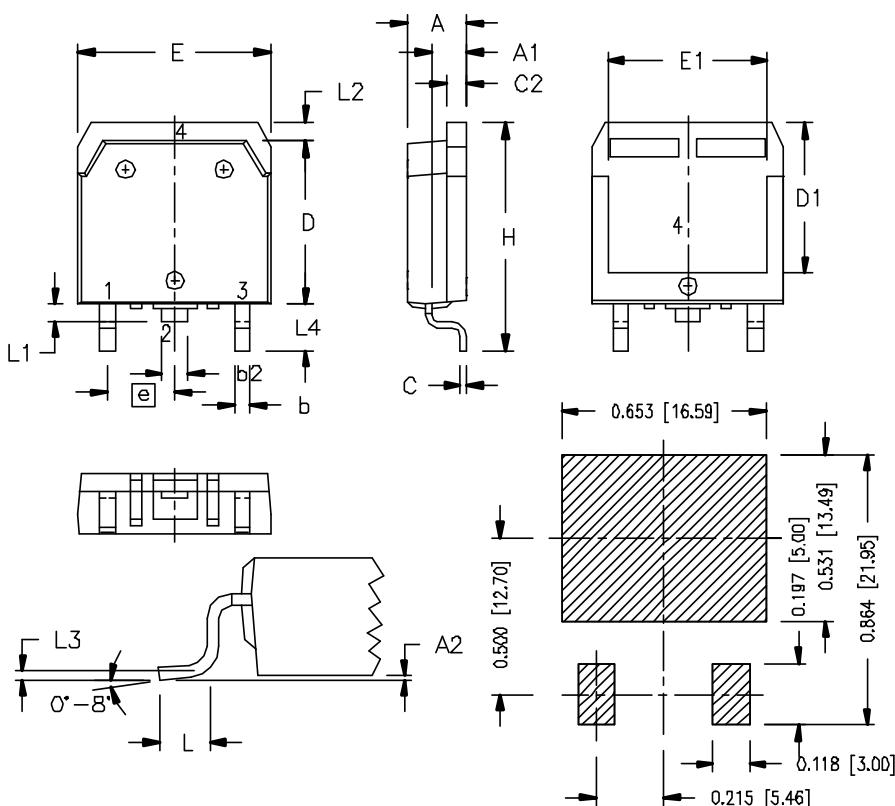
IGBT

Diode

1.1 1.25 V

460 280 mΩ

Outlines TO-268AA (D3Pak)



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.90	5.10	0.193	0.201
A1	2.70	2.90	0.106	0.114
A2	0.02	0.25	0.001	0.100
b	1.15	1.45	0.045	0.057
b2	1.90	2.10	0.075	0.083
C	0.40	0.65	0.016	0.026
C2	1.45	1.60	0.057	0.063
D	13.80	14.00	0.543	0.551
D1	12.40	12.70	0.488	0.500
E	15.85	16.05	0.624	0.632
E1	13.30	13.60	0.524	0.535
e	5.45 BSC		0.215 BSC	
H	18.70	19.10	0.736	0.752
L	2.40	2.70	0.094	0.106
L1	1.20	1.40	0.047	0.055
L2	1.00	1.15	0.039	0.045
L3	0.25 BSC		0.100 BSC	
L4	3.80	4.10	0.150	0.161

RECOMMENDED MINIMUM FOOT PRINT FOR SMD

